Application no. 10/826,752

APS01-002B

December 19, 2005

TO:

issioner for Patents

Box 1450

Alexandria, VA 22313-1450

Attn:

Art Unit 2813 - Examiner Mitchell, James M

FROM:

George O. Saile, Reg. No. 19,572

28 Davis Avenue

Poughkeepsie, N.Y. 12603

SUBJECT:

Serial #:

10/826,752

File Date:

04/16/2004

Inventor:

Romeo Emmanuel P. Alvarez

Examiner:

Mitchell, James M.

Art Unit:

2813

Title:

Method for Forming a Wafer Level Chip Scale Package and

Package Formed Thereby

## RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

This is in response to the Restriction Requirement in the Office Action dated Oct.

17, 2005. In that office action, restriction was required to one of the following Inventions under

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents P.O. Box 1450, Alexandria, VA 22313-1450 on Dec. 19, 2005.

Signature\_

Stephen B. Ackerman, Reg. No. 37,761

Date: Dec. 19, 2005